2SB1488

Silicon PNP triple diffusion planar type

For power switching

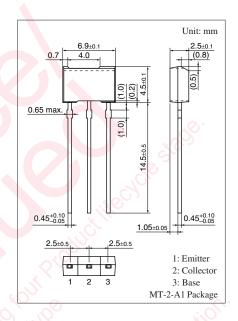
■ Features

- High forward current transfer ratio hFE
- High-speed switching
- High collector-base voltage (Emitter open) V_{CBO}
- Allowing supply with the radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	ymbol Rating	
Collector-base voltage (Emitter open)	V_{CBO}	-400	V
Collector-emitter voltage (Base open)	V_{CEO}	-400	V
Emitter-base voltage (Collector open)	V_{EBO}	-7	V
Collector current	I_{C}	- 0.5	A
Peak collector current	I_{CP}	-1	A
Collector power dissipation *	P_{C}	1	W
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Note) *: Print circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

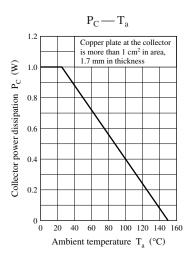
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-400	250		V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -400 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -100 \text{ V}, I_{B} = 0$	1.90		-1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -5 \text{ V}, I_{C} = -50 \text{ mA}$	80		280	_
	h _{FE2}	$V_{CE} = -5 \text{ V}, I_{C} = -300 \text{ mA}$	10			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		- 0.25	- 0.50	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		- 0.8	-1.2	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 0.1 \text{ A}, f = 200 \text{ MHz}$		25		MHz
Turn-on time	t _{on}	$I_C = -100 \text{ mA}, R_L = 1.5 \text{ k}\Omega$		0.4	1.0	μs
Storage time	t _{stg}	$I_{B1} = -10 \text{ mA}, I_{B2} = 10 \text{ mA}$		5.5	6.5	μs
Fall time	t _f	$V_{CC} = -150 \text{ V}$		0.5	1.0	μs
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20	40	pF

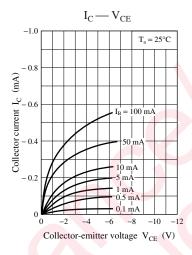
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

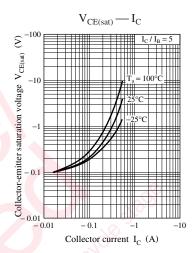
2. *: Rank classification

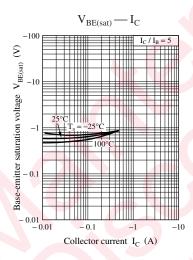
Rank	Р	Q
h_{FE1}	80 to 160	130 to 280

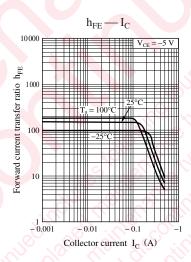
Panasonic

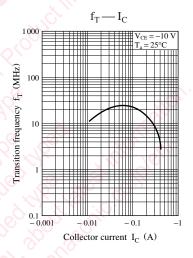


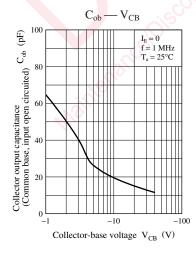


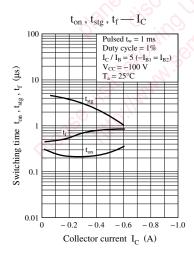












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